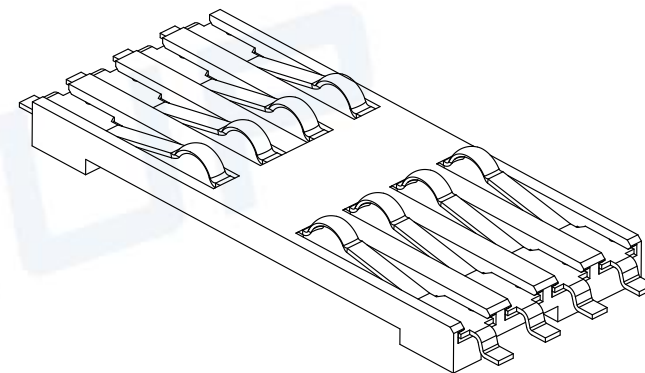


RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)

Coplanarity of metal solder pins  $\leq 0.15\text{mm}$   
Recommending of solder paste thickness  $> 0.15\text{mm}$

REV.	DESCRIPTION OF REVISIONS	APPR.	CHEC.	DRAW.	DATE
△	NEW			Zoey	2009/09/15
△	Original Model C739-3			Xufang	2024/01/09



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 23.62Lx10.16Wx1.55mm

Weight: Approx 0.50±0.1g

Durability: 100,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C, 30sec.Max

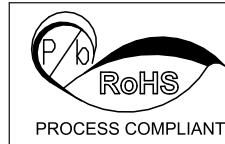
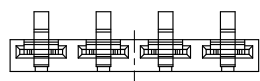
IR reflow: 260°C, 10sec.Max

Manual soldering: 370°C, 3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH



ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area:Gold plated

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5*
X.X	±0.25	X.X*	±4*
X.XX	±0.15	X.XX*	±3*
X.XXX	±0.10	X.XXX*	±2*

NAME: **Smart Card Connector**  
MODEL NO: **MUP-C7039-03**  
TYPE: **w/o post H1.55**

PROJ.	UNIT	SCALE	DRAWN	Zoey	Sep.15.2009	DWG NO.:	DWG-C7039-03-01
⊕	MM	1:1	CHECKED	Jay	Sep.15.2009	SHEET	1/1
CUSTOMER DRAWING			APPROVAL	Jun	Sep.15.2009	REVISION	2